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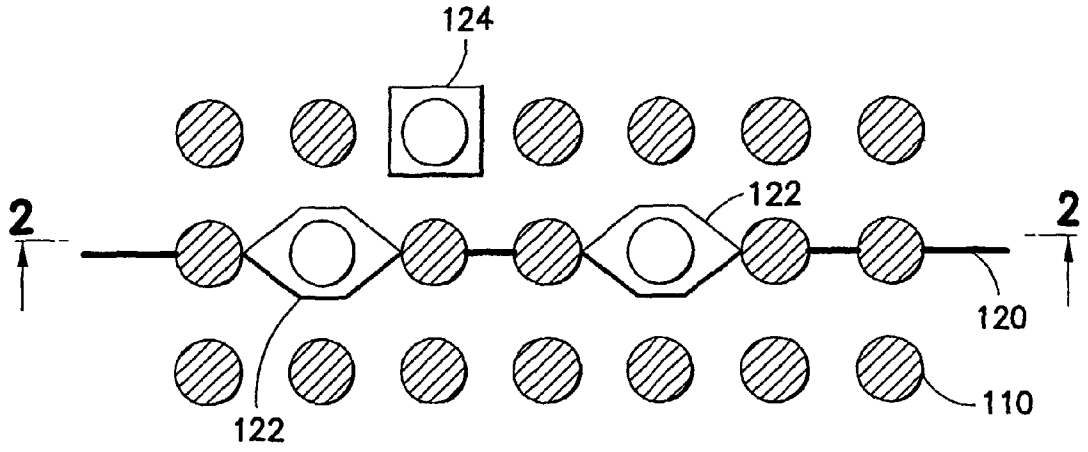
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(54) Title: SELECTIVE CONNECTION IN IC PACKAGING



(57) Abstract: In an integrated circuit package employing solder bump technology, a metal wiring placed on the surface of a substrate below an array of bonding pads is split and displaced from its axis at selected locations to preserve electrical continuity, but to also lower the height of an insulating solder mask layer at those locations.

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